UTAC Selects Teradyne's J750 Mixed Signal Option - Widens Range Of Low-cost Test For Consumer ICs

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BOSTON, MASSACHUSETTS - February 20, 2003 - Teradyne announced today that United Test and Assembly Center Ltd. (UTAC) of Singapore has added the Mixed Signal Option (MSO) to its existing Integra 750 testers. The equipment upgrade enables UTAC to improve its capacity utilization and to test a wider range of ICs, including chips that power lifestyle consumer electronics. UTAC's selection was based on the wide bandwidth, high density and best test economics of Teradyne's J750 boosted by the MSO. The J750's MSO represents the highest test density instrument with the most source and capture channels to test more devices in parallel, at reduced overall cost of test.

"The landscape of consumer network and communication products is evolving to focus on baseband," said Y.H Chok, Vice President, Test Operations at UTAC. "Baseband will spur the growth of next generation networked lifestyle consumer electronics, such as digital TV, DVD, PC, wireless home networking, and multi-purpose handheld devices. Teradyne's J750 with MSO positions UTAC to add lifestyle consumer electronics as another revenue dimension that fits with the Broadband, Mobile/ Wireless ("BM/W") strategy."

UTAC's Chok added, "As a test services provider, utilization and cost of test are critical to our business. The J750 with MSO enables UTAC to uphold the commitment to provide the best service quality and test economics to our customers."

"We targeted the development of the MSO against the baseband, mobile, and lifestyle consumer markets with the intention of providing a high-volume, cost-sensitive test solution," said Rick Nohelty, Teradyne's J750 MSO Product Marketing Manager. "The high instrument density of the MSO is specific to Teradyne and as such it differentiates our mixed signal test solution in the marketplace. We're uniquely positioned to provide customers, like UTAC, a higher parallel device test at the best cost of test."

About the Integra J750

The J750's high-throughput parallel test capability provides as high as 95% parallel test efficiency for up to 32 devices. The zero footprint system delivers up to 1,024 I/O channels contained in a test head, and offers a suite of options, including the Converter Test Option, Memory Test Option, Redundancy Analysis, and Mixed Signal Option, that broaden the range of testing capabilities. The system also features IG-XL test software that combines the power and performance of the latest PC technology and Windows NT operating system with the familiarity of standard Windows productivity tools, such as Microsoft Excel and Visual Basic. The J750's small footprint and high parallel test throughput provide the most economical approach to testing complex VLSI devices with embedded memory and analog cells.

About United Test and Assembly Center Ltd (UTAC)

United Test and Assembly Center Limited (UTAC) provides full turnkey solutions in assembly and testing of memory and mixed signal semiconductors. UTAC's "BM/W" strategy focuses on accelerating penetration into and expansion in the Broadband and Mobile/ Wireless communications industries. UTAC's customer base comprises leading and emerging global designers and manufacturers of semiconductors that power computing, communication, and consumer electronic appliances. UTAC is headquartered in Singapore, and is supported by a global sales and marketing network in Italy, Israel, Japan, and the United States. For further information, visit http://www.utac.com.sg/.

About Teradyne

Teradyne (NYSE: TER) manufactures Automatic Test Equipment and interconnection systems that deliver competitive advantage to the world's leading semiconductor, electronics, automotive and network systems companies. Teradyne had sales of $1.22 billion in 2002 and employs about 7200 people worldwide. For more information visit http://www.teradyne.com/.